



SOT1118D

DFN2020D-6: plastic, thermally enhanced ultra thin and small outline package; no leads; 6 terminals; body 2 x 2 x 0.65 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HUSON6
Package type industry code	DFN2020D-6
Package style descriptive code	HUSON (thermal enhanced ultra thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	16-7-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.9	-	2	2.1	mm
E	package width		1.9	-	2	2.1	mm
A	seated height		[tbd]	-	[tbd]	0.65	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	6	-	



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2. Package outline

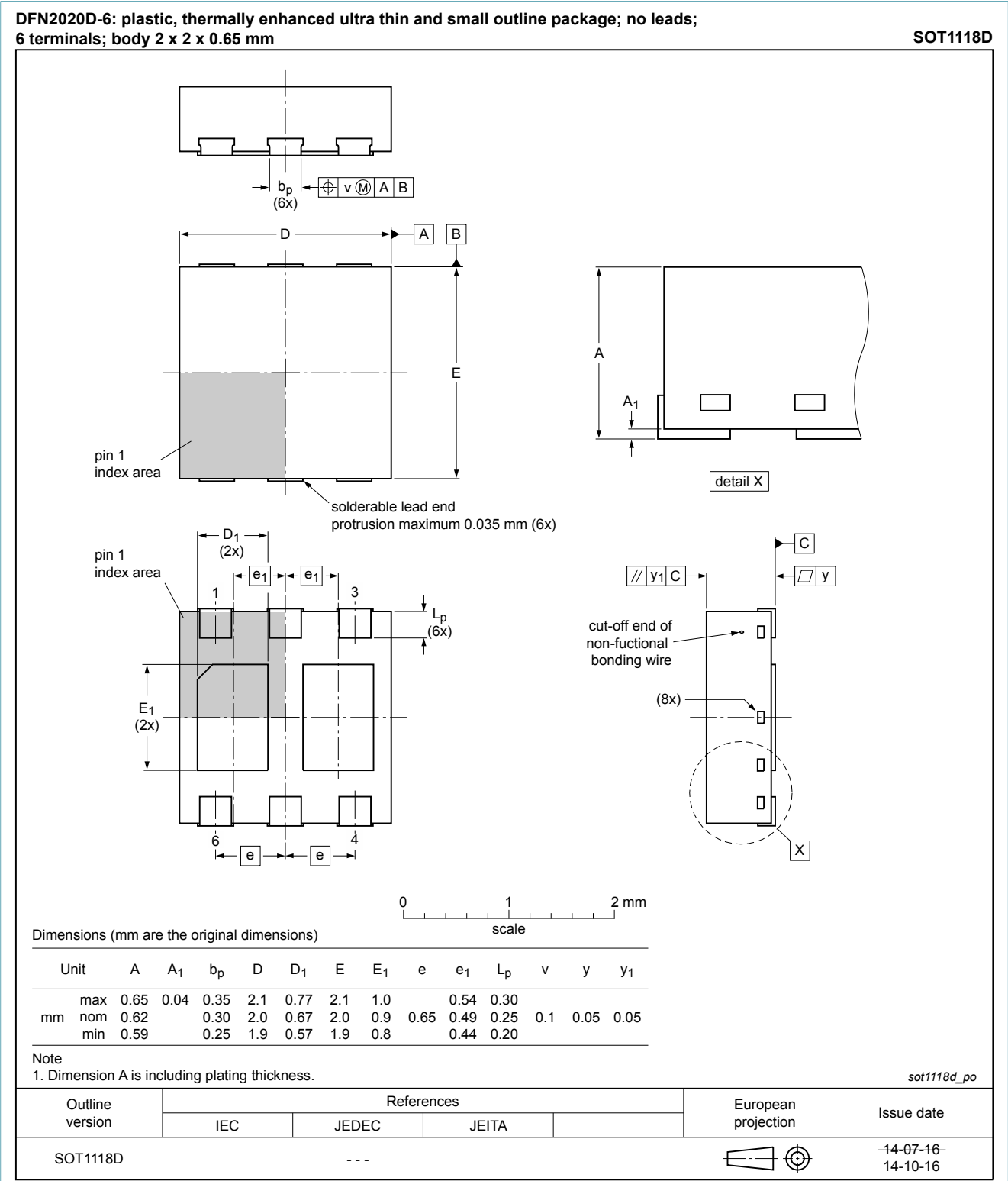
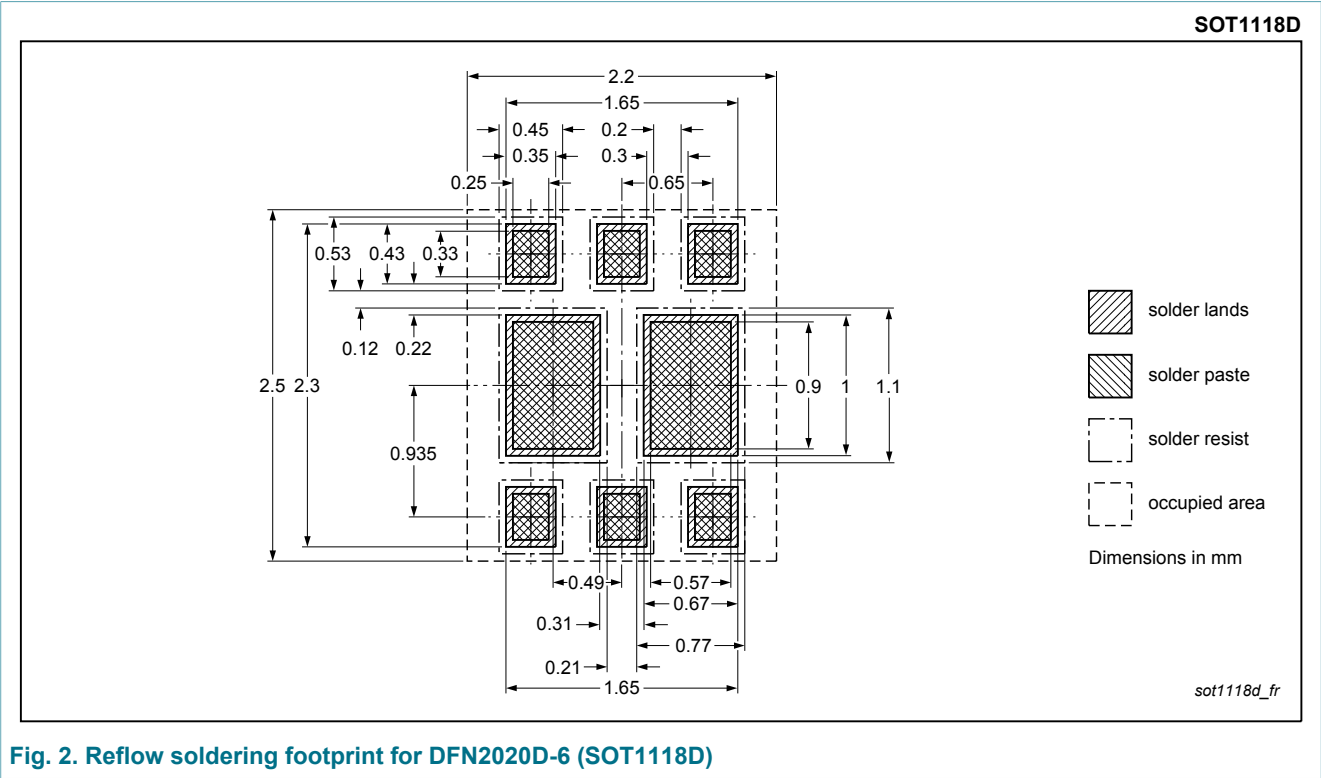


Fig. 1. Package outline DFN2020D-6 (SOT1118D)

DFN2020D-6: plastic, thermally enhanced ultra thin and small outline package; no leads; 6 terminals; body 2 x 2 x 0.65 mm

3. Soldering



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4. Legal information

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